# **DRC4114Y** (Tentative)

### Silicon NPN epitaxial planar type

For digital circuits

■ Packaging

Radial type: 5000 pcs / carton

#### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	50	V	
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	50	V	
Collector current	$I_{C}$	100	mA	
Total power dissipation	P <sub>T</sub>	300	mW	
Junction temperature	$T_j$	150	°C	
Storage temperature	T <sub>stg</sub>	-55 to +150	°C	

#### ■ Package

Code

NS-B1-B

• Pin Name

1: Emitter

2: Collector

3: Base

■ Marking Symbol: NC

#### ■ Internal Connection

$$B \circ \begin{matrix} R_1 \\ R_2 \end{matrix} \qquad \circ E$$

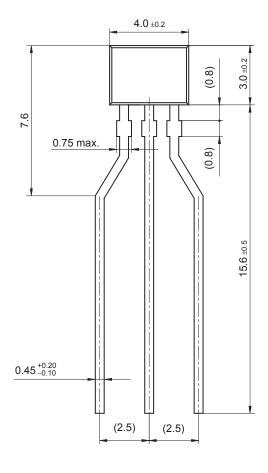
Resistance	R <sub>1</sub>	10	kΩ
value	$R_2$	47	kΩ

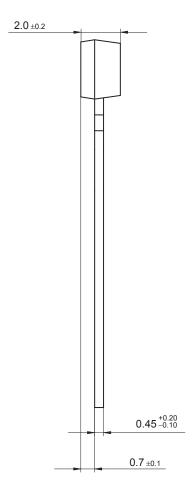
#### ■ Electrical Characteristics $T_a = 25$ °C±3°C

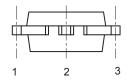
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	$V_{CBO}$	$I_{\rm C} = 10 \ \mu A, I_{\rm E} = 0$	50			V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_{\rm C} = 2 \text{ mA}, I_{\rm B} = 0$	50			V
Collector-base cutoff current (Emitter open)	I <sub>CBO</sub>	$V_{CB} = 50 \text{ V}, I_{E} = 0$			0.1	μΑ
Collector-emitter cutoff current (Base open)	$I_{CEO}$	$V_{CE} = 50 \text{ V}, I_{B} = 0$			0.5	μΑ
Emitter-base cutoff current (Collector open)	I <sub>EBO</sub>	$V_{EB} = 6 \text{ V}, I_{C} = 0$			0.2	mA
Forward current transfer ratio	$h_{FE}$	$V_{CE} = 10 \text{ V}, I_{C} = 5 \text{ mA}$	80			_
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = 10 \text{ mA}, I_B = 0.5 \text{ mA}$			0.25	V
Input voltage (ON)	V <sub>I(on)</sub>	$V_{CE} = 0.2 \text{ V}, I_{C} = 5 \text{ mA}$	1.7			V
Input voltage (OFF)	V <sub>I(off)</sub>	$V_{CE} = 5 \text{ V}, I_{C} = 100  \mu\text{A}$			0.5	V
Input resistance	$R_1$		-30%	10	+30%	kΩ
Resistance ratio	$R_1/R_2$		0.17	0.21	0.25	_

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

NS-B1-B Unit: mm







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